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## **Keiron's Laser-Driven LiFT Technology Wins 2026 NPI Award for Transforming SMT Printing**

**Eindhoven, Netherlands— March 2026** — Keiron Printing Technologies, a global innovator in advanced electronics manufacturing solutions, has been named a 2026 NPI Award winner in the Screen/Stencil Printing category for its LiFT HF2 Digital Solder-Paste Printer.



The award recognizes Keiron's breakthrough LiFT (Laser-Induced Forward Transfer) technology, which replaces traditional stencil- and nozzle-based solder paste deposition with a laser-driven, fully digital, non-contact process. By eliminating stencils, nozzles, ejectors, and other mechanical contact points, LiFT removes a major source of process variability while directly addressing one of the most common contributors to assembly defects: inconsistent solder paste application.

The Keiron HF2 LiFT Printer enables precise, repeatable solder paste deposition down to nanoliter volumes while working with standard solder pastes and accepting common CAD, Gerber, and ODB++ file formats. This allows manufacturers to implement digital solder paste printing without changing materials or disrupting established workflows. With no stencils to fabricate, clean, or store, changeovers can be completed in minutes—making the HF2 particularly well suited for high-mix, low-volume, and NPI-focused production environments.

A key differentiator of the HF2 is its integrated Solder Paste Volume Metrology (SPVM), which measures every deposit in real time during the printing process. This built-in verification capability improves first-pass yield and reduces rework and scrap without requiring a separate SPI system. The contactless architecture also avoids common reliability challenges such as clogging, mechanical wear, and alignment drift associated with conventional printing methods.

“This award validates the shift toward truly digital solder paste deposition,” said Brian Duffey, President of Keiron Technologies USA. “LiFT technology removes mechanical variability from one of the most critical steps in SMT assembly. With the HF2, manufacturers gain unprecedented control, flexibility, and repeatability—without changing their materials or core processes.”

Presented by CIRCUITS ASSEMBLY, the NPI Awards celebrate leading-edge products that drive measurable advancements in electronics assembly. Winners are selected by an independent panel of industry engineers who evaluate innovation, functionality, and real-world production impact.

For more information about Keiron’s industry revolutionizing technology, visit [www.keirontechnologies.com](http://www.keirontechnologies.com).

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#### **About Keiron Printing Technologies**

Keiron Printing Technologies is a global innovator in advanced electronics manufacturing equipment, specializing in fully digital, LiFT-based precision solder paste printing solutions. Designed for modern, high-performance production environments, Keiron’s technology enables zero-waste, high-accuracy manufacturing while supporting rapid innovation and sustainable growth.